ASSOCIATION CONNE	© Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					Iaterials and I	als and Mfg Information				
upplier Info	rmation															
Company name* Company unique ID				que ID	ID U		Unique ID Authority					Response Date*				
nsemi												2024-04-24				
Contact Name		Title - Contact			P	Phone - Contact*				Email	Email - Contact*					
Product-Env-St	ewards	Product Enviro Compliance			N	NA				Produ	Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Re				tle - Representative			Phone - Representative*				Email	Email - Representative*				
Product-Env-St	ewards	Product Enviro Compliance			N	NA				Produ	Product-Env-Stewards@onsemi.com					
Requ	Requester Item Number Mfr Iter		Item Number Mfr Item Name				Effective Date	Version Man		anufacturing Site		Weig	ht*	UOM	Unit Type	
		AX8052F100-3-TW30 AX8052F100-3-T 7531A die			ΓW30, Microcontroller	with 2	2024-04-24	04-24 PHG				54.89 mg		mg	Each	
Ianufacturi	ng Proccess Informa	tion														
Termi	nal Plating / Grid Array Ma	Plating / Grid Array Material Term		rminal Base Alloy J-STD-0		ing Peak Proc		cess Body T	ss Body Temperature Max Time		Peak Temper	eak Temperature		Number of Reflow Cycles		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		1		260		С	30	seco	nds	3				
Comments							-									
vel 1 - maximu	m time at peak temperatu	re during so	ldering is 10-3	0 seconds												
or more inform	nation regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).												
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of							
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	eneous Material Weight Unit of Measure L		Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die 3.28 mg		mg	Supplier	Silicon (Si)	7440-21-3		3.28	mg
Die Attach	0.6	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.12	mg
			Supplier	Silver (Ag)	7440-22-4		0.48	mg
Lead Frame	26.96	mg	Supplier	Silver (Ag)	7440-22-4		0.5392	mg
			Supplier	Iron (Fe)	7439-89-6		0.5931	mg
			Supplier	Copper (Cu)	7440-50-8		25.8277	mg
Mold Compound-Black	22.31	mg		Epoxy Phenol Resin	proprietary data		2.3425	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		19.9674	mg
Plating	1.2	mg	Supplier	Palladium (Pd)	7440-05-3		0.0288	mg
			В	Nickel (Ni)	7440-02-0		1.056	mg
			Supplier	Gold (Au)	7440-57-5		0.1152	mg
Wire Bond - Au	0.54	mg	Supplier	Gold (Au)	7440-57-5		0.54	mg